

# **ABSTRACT**

The object of the present invention is to provide a copper foil with an ultra thin resin layer for a printed wiring board without roughening treatment. In order to achieve the object, there is adopted a copper foil with an ultra thin adhesive layer for a printed wiring board 1 or the like, which is a copper foil provided with an ultra thin primer resin layer for securing good laminating adhesiveness with a resin base material on one side of a copper foil 3 without roughening treatment, characterized in that a silane coupling agent layer 2 is formed on a surface of the copper foil without the roughening treatment having a surface roughness (Rz) of 2  $\mu\text{m}$  or below, and an ultra thin primer resin layer 4 having a converted thickness of 1 to 5  $\mu\text{m}$  is formed on the silane coupling agent layer 2.